

10A, 650V N-CHANNEL MOSFET

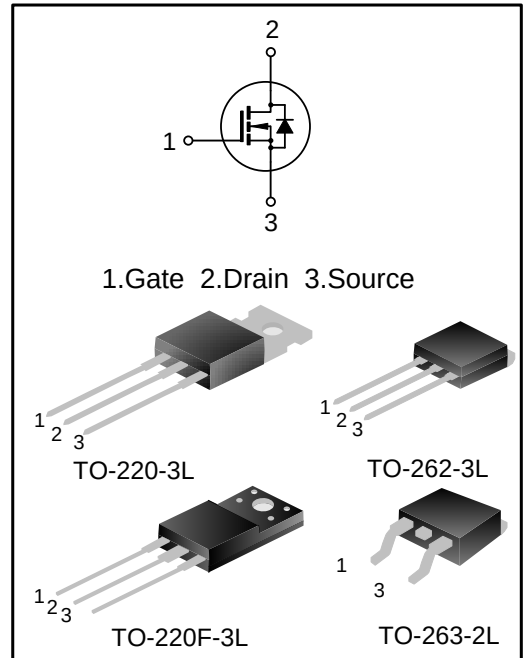
GENERAL DESCRIPTION

SVF10N65T/F/K/S is an N-channel enhancement mode power MOS field effect transistor which is produced using Silan proprietary F-Cell™ structure VDMOS technology. The improved process and cell structure have been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are widely used in AC-DC power supplies, DC-DC converters and H-bridge PWM motor drivers.

FEATURES

- 10A, 650V, $R_{DS(on)}(typ.)=0.80\Omega@V_{GS}=10V$
- Low gate charge
- Low C_{rss}
- Fast switching
- Improved dv/dt capability



ORDERING INFORMATION

Part No.	Package	Marking	Hazardous Substance Control	Packing Type
SVF10N65T	TO-220-3L	SVF10N65T	Pb free	Tube
SVF10N65F	TO-220F-3L	SVF10N65F	Pb free	Tube
SVF10N65K	TO-262-3L	SVF10N65K	Pb free	Tube
SVF10N65S	TO-263-2L	SVF10N65S	Halogen free	Tube
SVF10N65STR	TO-263-2L	SVF10N65S	Halogen free	Tape&Reel

ABSOLUTE MAXIMUM RATINGS (T_A=25°C UNLESS OTHERWISE NOTED)

Characteristics		Symbol	Ratings				Unit
			SVF10N 65F	SVF10N 65T	SVF10N 65K	SVF10N 65S	
Drain-Source Voltage		V _{DS}	650				V
Gate-Source Voltage		V _{GS}	±30				V
Drain Current	T _C =25°C	I _D	10				A
	T _C =100°C		6.3				
Drain Current Pulsed		I _{DM}	40				A
Power Dissipation(T _C =25°C)		P _D	50	156	150	150	W
-Derate above 25°C			0.4	1.25	1.20	1.20	W/°C
Single Pulsed Avalanche Energy (Note1)		E _{AS}	618				mJ
Operation Junction Temperature Range		T _J	-55~+150				°C
Storage Temperature Range		T _{stg}	-55~+150				°C

THERMAL CHARACTERISTICS

Characteristics	Symbol	Ratings				Unit
		SVF10N 65F	SVF10N 65K	SVF10N 65T	SVF10N 65S	
Thermal Resistance,Junction-to-Case	R _{θJC}	2.5	0.83	0.8	0.83	°C/W
Thermal Resistance,Junction-to-Ambient	R _{θJA}	62.5	62.5	62.5	62.5	°C/W

ELECTRICAL CHARACTERISTICS (T_J=25°C UNLESS OTHERWISE NOTED)

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Drain -Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V,I _D =250μA	650	--	--	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =650V,V _{GS} =0V	--	--	1.0	μA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±30V,V _{DS} =0V	--	--	±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{GS} = V _{DS} ,I _D =250μA	2.0	--	4.0	V
Static Drain- Source On State Resistance	R _{DS(on)}	V _{GS} =10V,I _D =5.0A	--	0.8	1.0	Ω
Input Capacitance	C _{iss}	V _{DS} =25V,V _{GS} =0V, f=1.0MHz	--	1100	--	pF
Output Capacitance	C _{oss}		--	130	--	
Reverse Transfer Capacitance	C _{rss}		--	13	--	
Turn-on Delay Time	t _{d(on)}	V _{DD} =325V,I _D =10A, R _G =25Ω (Note 2,3)	--	21	--	ns
Turn-on Rise Time	t _r		--	41	--	
Turn-off Delay Time	t _{d(off)}		--	82	--	
Turn-off Fall Time	t _f		--	43	--	
Total Gate Charge	Q _g	V _{DS} =520V,I _D =10A, V _{GS} =10V (Note 2,3)	--	29	--	nC
Gate-Source Charge	Q _{gs}		--	6.2	--	
Gate-Drain Charge	Q _{gd}		--	13	--	

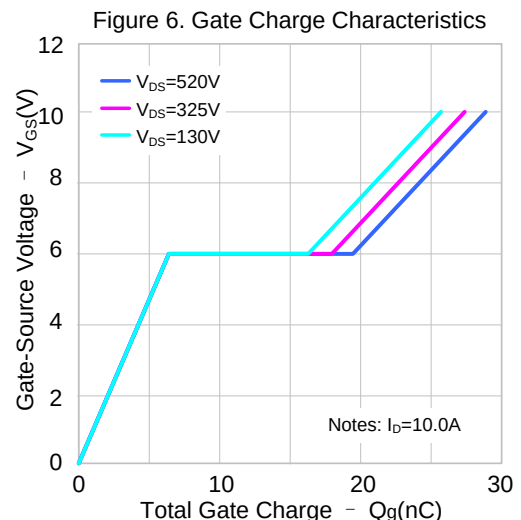
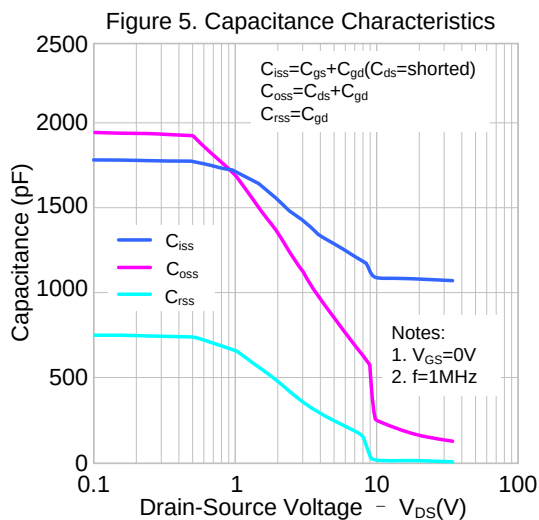
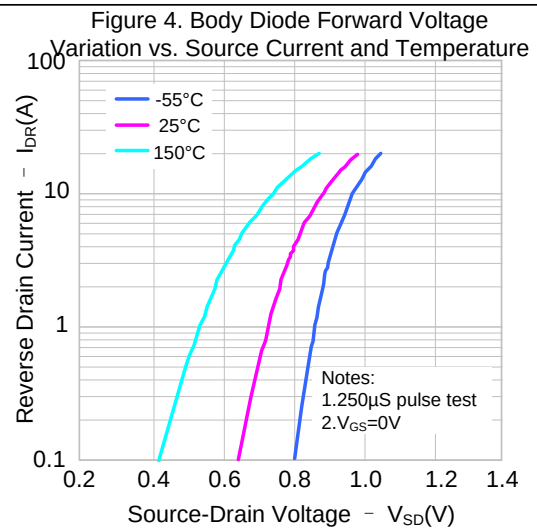
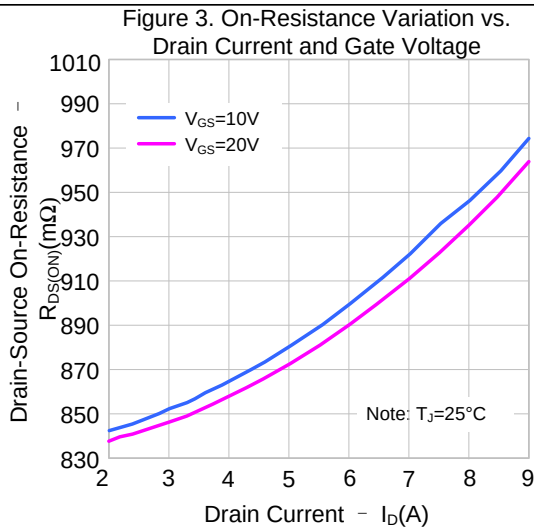
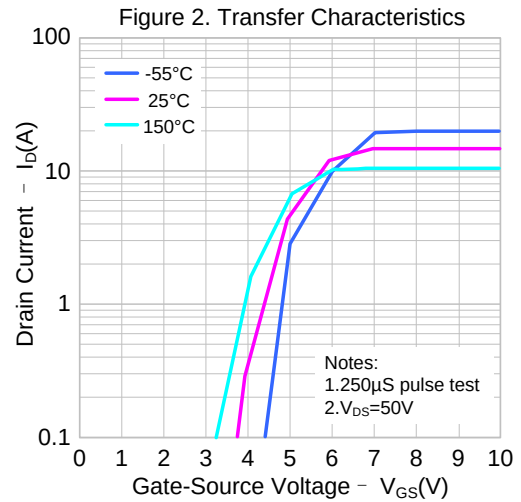
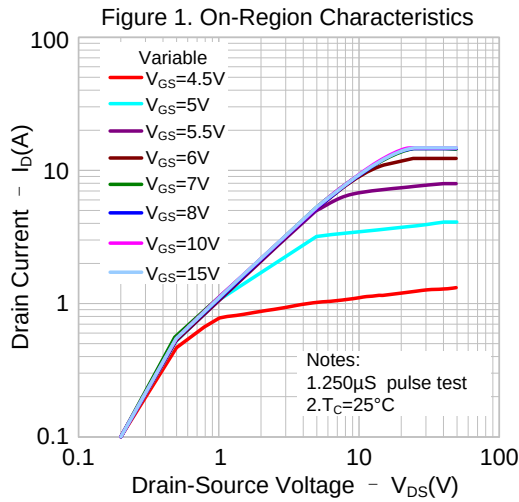
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	I_S	Integral Reverse p-n Junction Diode in the MOSFET	--	--	10	A
Pulsed Source Current	I_{SM}		--	--	40	
Diode Forward Voltage	V_{SD}	$I_S=10A, V_{GS}=0V$	--	--	1.3	V
Reverse Recovery Time	T_{rr}	$I_S=10A, V_{GS}=0V,$ $di_F/dt=100A/\mu S$ (Note:2)	--	561	--	ns
Reverse Recovery Charge	Q_{rr}		--	4.3	--	μC

Notes:

1. $L=30mH, I_{AS}=6.0A, V_{DD}=100V, R_G=25\Omega$, starting $T_J=25^\circ C$;
2. Pulse Test: Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$;
3. Essentially independent of operating temperature.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS (CONTINUED)

Figure 7. Breakdown Voltage Variation vs. Temperature

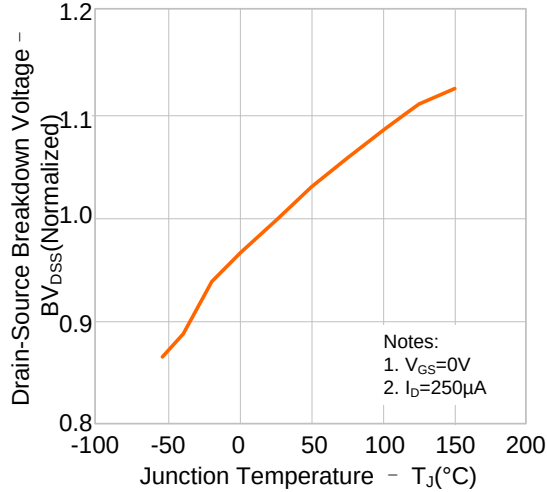


Figure 8. On-resistance vs. Temperature

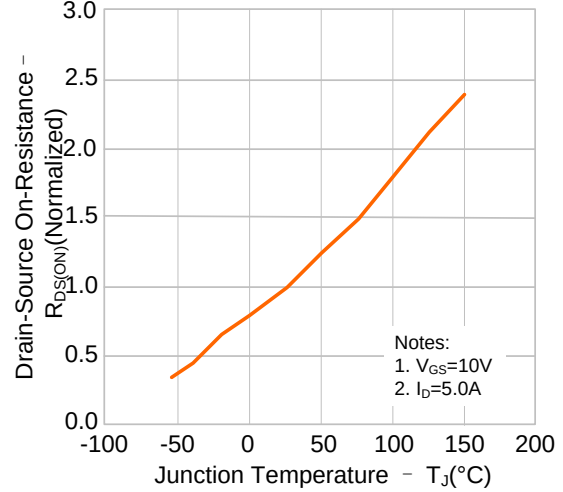


Figure 9-1. Max. Safe Operating Area(SVF10N65F)

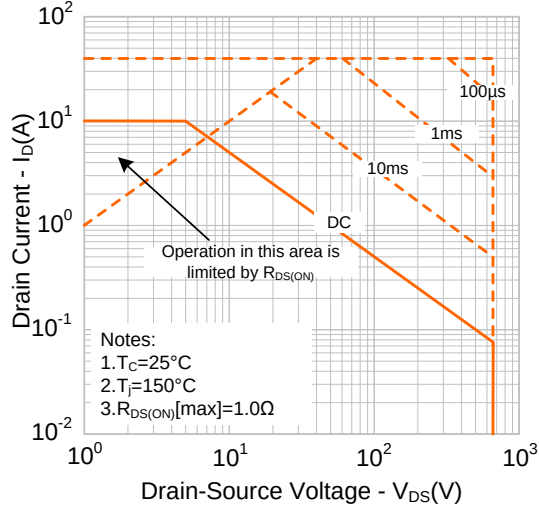


Figure 9-2. Max. Safe Operating Area(SVF10N65K)

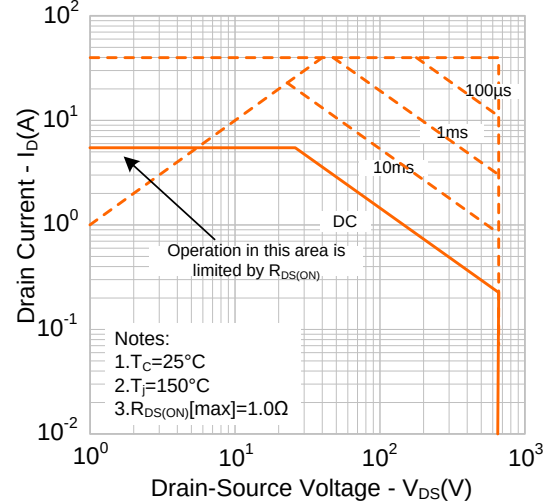


Figure 9-3. Max. Safe Operating Area(SVF10N65T)

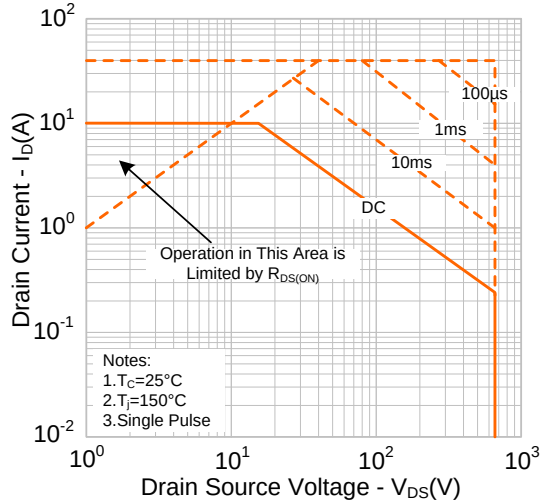
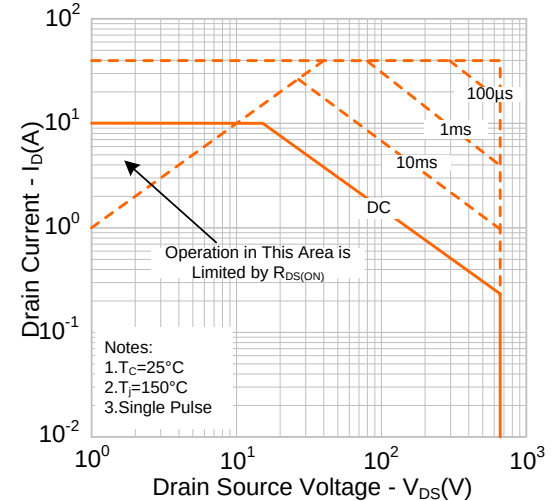
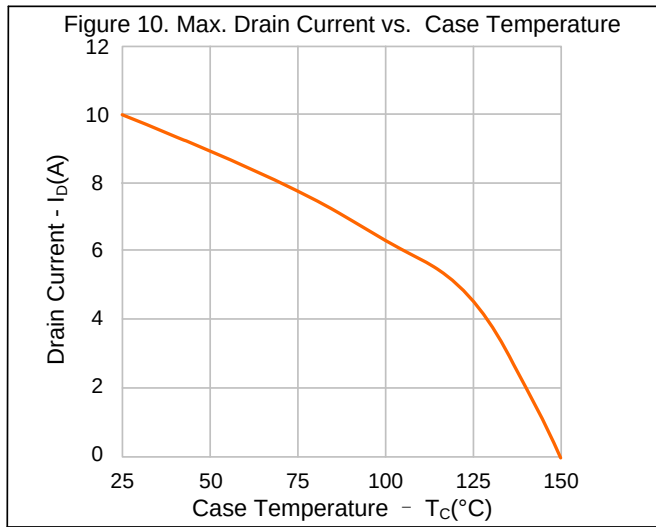


Figure 9-4. Max. Safe Operating Area(SVF10N65S)

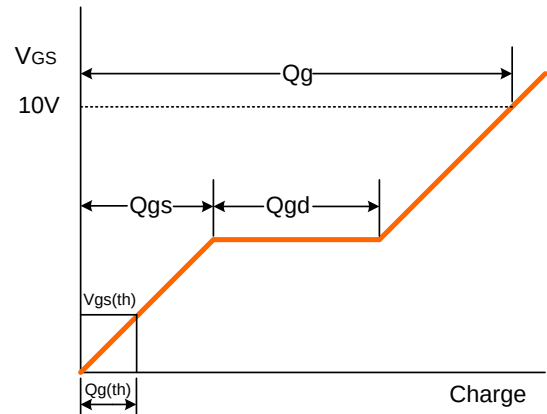
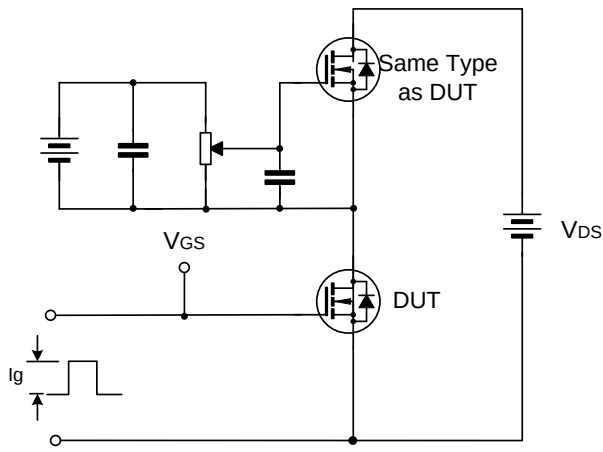


TYPICAL CHARACTERISTICS (CONTINUED)

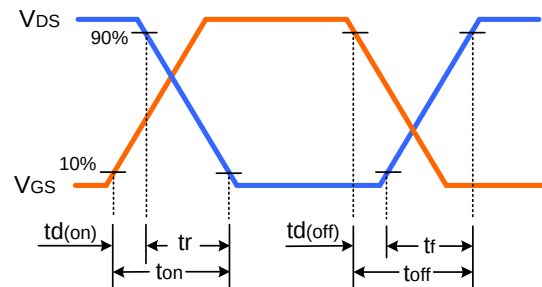
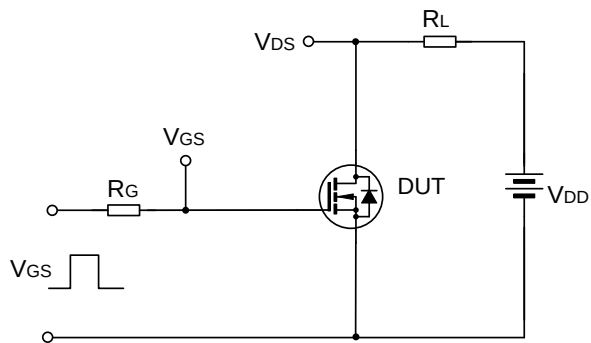


TYPICAL TEST CIRCUIT

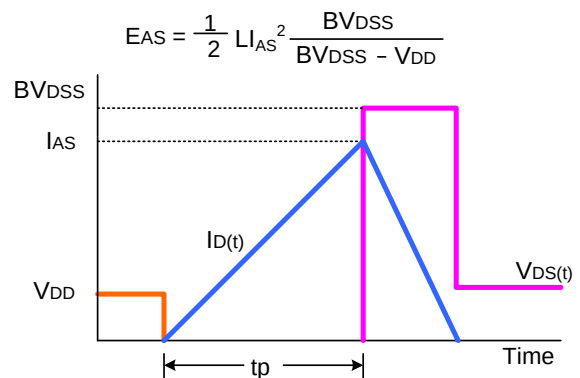
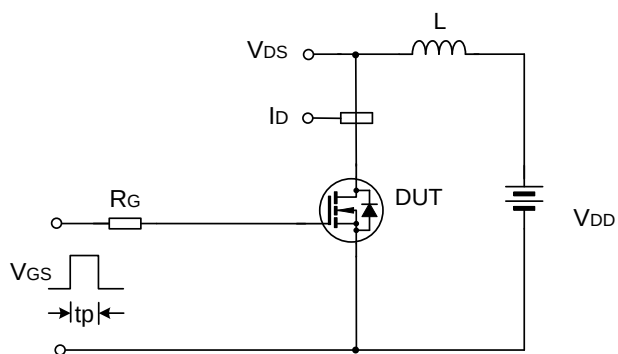
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveform



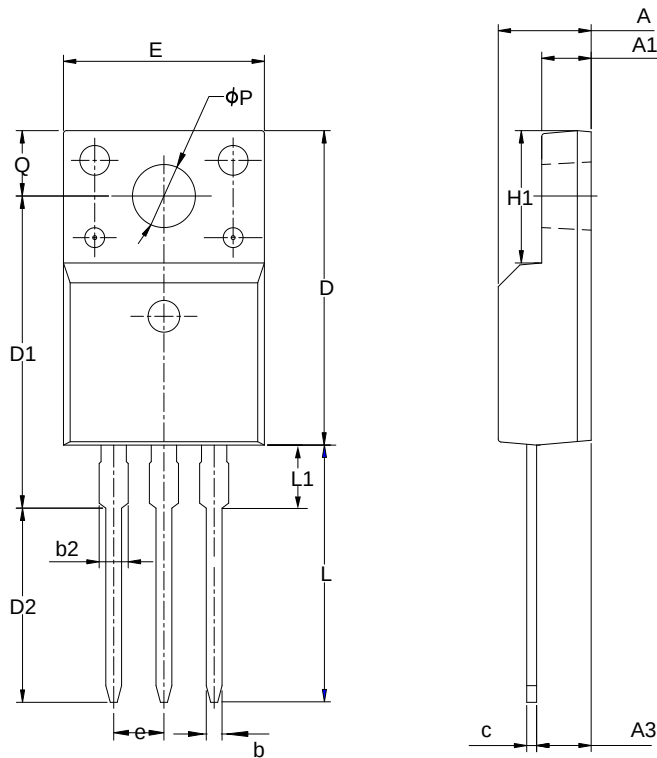
Unclamped Inductive Switching Test Circuit & Waveform



PACKAGE OUTLINE

TO-220F-3L

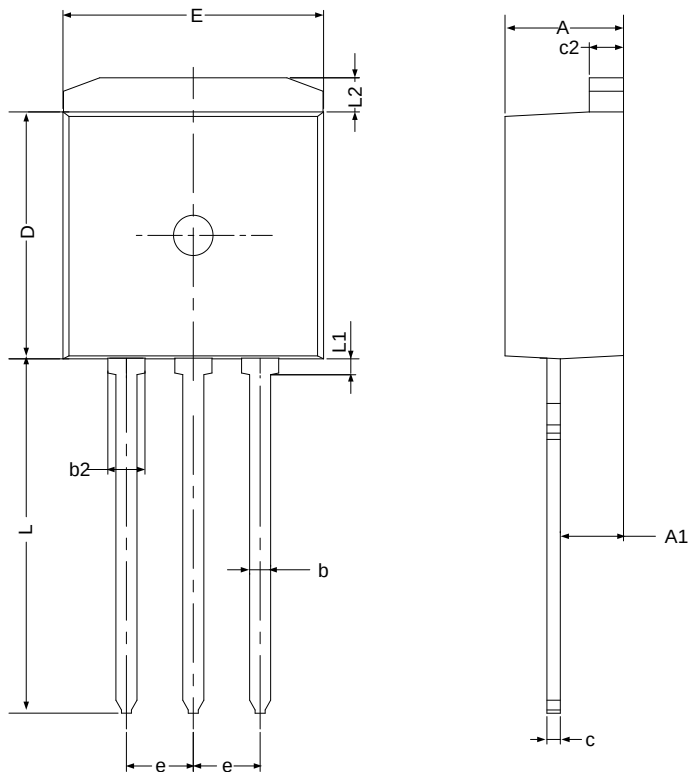
UNIT: mm



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.42	4.70	5.02
A1	2.30	2.54	2.80
A3	2.50	2.76	3.10
b	0.70	0.80	0.90
b2	—	—	1.47
c	0.35	0.50	0.65
D	15.25	15.87	16.25
D1	15.30	15.75	16.30
D2	9.30	9.80	10.30
E	9.73	10.16	10.36
e	2.54BSC		
H1	6.40	6.68	7.00
L	12.48	12.98	13.48
L1	—	—	3.50
ϕP	3.00	3.18	3.40
Q	3.05	3.30	3.55

TO-262-3L

UNIT: mm

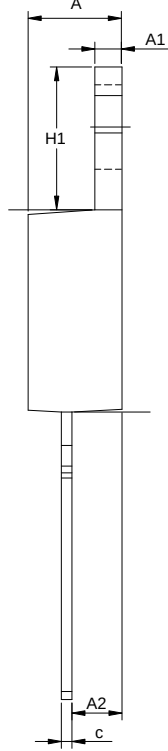
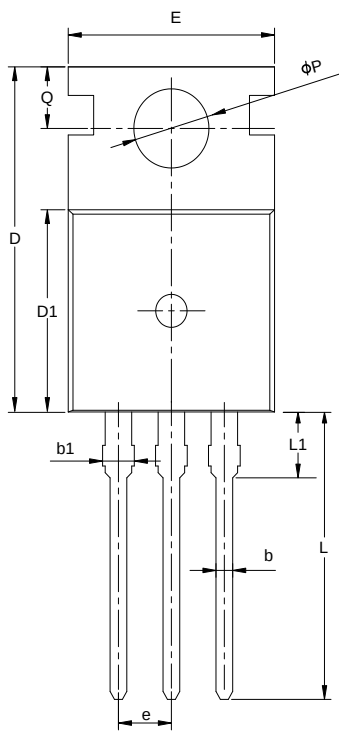


SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.30	4.50	4.70
A1	2.20	—	2.92
b	0.71	0.80	0.90
b2	1.20	—	1.50
c	0.34	—	0.65
c2	1.22	1.30	1.35
D	8.38	—	9.30
E	9.80	10.16	10.54
e	2.54 BSC		
L	12.80	—	14.10
L1	—	—	0.75
L2	1.12	—	1.42

PACKAGE OUTLINE(CONTINUED)

TO-220-3L

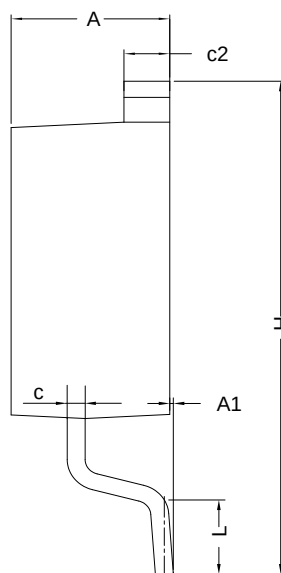
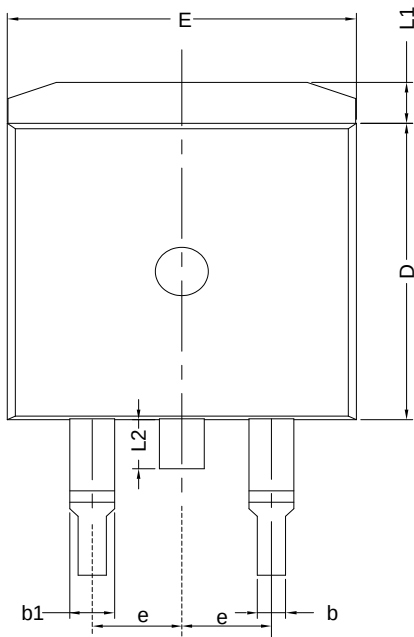
UNIT: mm



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.30	4.50	4.70
A1	1.00	1.30	1.50
A2	1.80	2.40	2.80
b	0.60	0.80	1.00
b1	1.00	—	1.60
c	0.30	—	0.70
D	15.10	15.70	16.10
D1	8.10	9.20	10.00
E	9.60	9.90	10.40
e	2.54BSC		
H1	6.10	6.50	7.00
L	12.60	13.08	13.60
L1	—	—	3.95
ϕP	3.40	3.70	3.90
Q	2.60	—	3.20

TO-263-2L

UNIT: mm



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.30	4.57	4.72
A1	0	0.10	0.25
b	0.71	0.81	0.91
c	0.30	—	0.60
c2	1.17	1.27	1.37
D	8.50	—	9.35
E	9.80	—	10.45
e	2.54BSC		
H	14.70	—	15.75
L	2.00	2.30	2.74
L1	1.12	1.27	1.42
L2	—	—	1.75

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Document Type: Datasheet

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Rev.: 2.5

Revision History:

1. Update the template of the datasheet

Rev.: 2.4

Revision History:

1. Add another solid figure of TO-220F-3L
2. Update the package outline of TO-262-3L

Rev.: 2.3

Revision History:

1. Modify the Electrical characteristics

Rev.: 2.2

Revision History:

1. Modify the package information of TO-220F-3L; Modify the package information of TO-220-3L

Rev.: 2.1

Revision History:

1. Modify the thermal characteristics

Rev.: 2.0

Revision History:

1. Modify the ordering information

Rev.: 1.9

Revision History:

1. Modify the ordering information

Rev.: 1.8

Revision History:

1. Change the schematic diagram of MOS

Rev.: 1.7

Revision History:

1. Modify "PACKAGE OUTLINE"

Rev.: 1.6

Revision History:

1. Add the package of TO-263-2L
-

Rev.: 1.5

Revision History:

1. Add the package of TO-262-3L
-

Rev.: 1.4

Revision History:

1. Modify the values of Trr and Qrr
-

Rev.: 1.3

Revision History:

1. Add the halogen free information of SVF10N65F
-

Rev.: 1.2

Revision History:

1. Modify "PACKAGE OUTLINE"
-

Rev.: 1.1

Revision History:

1. Modify "ELECTRICAL CHARACTERISTICS"
-

Rev.: 1.0

Revision History:

1. Original
-